



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. : 10/507,213
Confirmation : 5089
Applicant : Dietmar BIRGEL
Filed : September 15, 2004
Title : Method for populating and soldering a circuit board,
reflow oven and circuit board for such a method
TC/A.U. : 1793
Examiner : M. Aboagye
Docket No. : BIRG3004/FJD
Customer No. : 23364

RESPONSE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Introductory Comments

The following amendments and corresponding remarks are being submitted herewith pursuant to the provisions of 37 CFR 1.111 in response to the Office Action of February 4, 2008. The period for response to which is set to expire on June 4, 2008.